

Sheet 1 of 1

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICE

ATTY. DKT. NO.

SERIAL NO.

219.40779X00

INFORMATION DISCLOSURE STATEMENT
BY APPLICANT

(Use several sheets if necessary)

APPLICANT

B. CHANDRAN ET AL.

FILING DATE

GROUP

December 21, 2001

2827

U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
JBU	AA 5,369,551	11/29/94	Gore et al.			11/08/93
	AB 5,872,401	02/16/99	Huff et al.			02/29/96
	AC 5,889,652	03/30/99	Turturo			04/21/97
	AD 5,931,371	08/03/99	Pao et al.			01/16/97
	AE 5,936,304	08/10/99	Lii et al.			12/10/97
JBU	AF 6,049,124	04/11/00	Raiser et al.			12/10/97
	AG					
	AH					
	AI					
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	AL					

FOREIGN PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation/Abstract	
						Yes	No
	AM						
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

	AU	
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Examiner

John B. Vigorini

Date Considered

June 28, 2003

10/023819
12/21/01

Sheet 1 of 1

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U.S. PATENT DOCUMENTS

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
BK	AA 5,369,551	11/29/94	Gore et al.	361	767	11/08/93
	AB 5,872,401	02/16/99	Huff et al.	257	758	02/29/96
	AC 5,889,652	03/30/99	Turturro	361	719	04/21/97
	AD 5,931,371	08/03/99	Pao et al.	228	180.22	01/16/97
	AE 5,936,304	08/10/99	Lii et al.	257	778	12/10/97
	AF 6,049,124	04/11/00	Raiser et al.	257	737	12/10/97
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OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

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Examiner

John B. Vigorlin

Date Considered

April 29, 2003

Paper No. 0403a

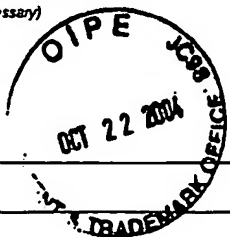
10/023819
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Complete if Known

Application Number	10/023,819
Filing Date	December 21, 2001
First Named Inventor	Chandran, Biju
Group Art Unit	2827 2841
Examiner Name	Vigushin, John

Sheet 1 of 1

Attorney Docket No: 884.A27US1

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<i>[Signature]</i>	US-6,402,012	06/11/2002	Bolduc, T. D.	228	180.22	11/08/1999
<i>[Signature]</i>	US-6,555,052	04/29/2003	Soga, T., et al.	420	560	03/07/2001

FOREIGN PATENT DOCUMENTS

Examiner Initials *	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS

Examiner Initials *	Cite No ¹	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
<i>[Signature]</i>		HONG, B. Z., "Thermal Fatigue Analysis of CBGA Package with Lead-Free Solder Fillets", <u>Proceedings of the 1998 Intersociety Conference on Thermal Phenomena</u> , (Aug., 1998), 205-211	
<i>[Signature]</i>		KARIM, Z. S., et al., "Lead-Free Bump Interconnections for Flip-Chip Applications", <u>Proceedings of the 2000 IEEE/CPMT International Electronics Manufacturing Technology Symposium</u> , (Jan., 2000), 274-278	
<i>[Signature]</i>		WANG, T., et al., "Studies on A Novel Flip-Chip Interconnect Structure-Pillar Bump", <u>Proceedings of the 2001 Electronic Components and Technology Conference</u> , (Apr., 2001), 5 p.	
<i>[Signature]</i>		XIAO, G., et al., "The Effect of Cu Stud Structure and Eutectic Solder Electroplating on Intermetallic Growth and Reliability of Flip-Chip Solder Bump", <u>Proceedings of the 2000 Electronic Components and Technology Conference</u> , (Sep., 2000), 54-59	

Paper No: 1004

EXAMINER

John B. Vigushin

DATE CONSIDERED

April 08, 2005

Substitute Disclosure Statement Form (PTO-1449)

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